Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.032”**

**ANODE**

**.027” x .027”**

**.032”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .027” X .027”**

**Backside Potential: CATHODE**

**Mask Ref: CPD76X**

**APPROVED BY: DK DIE SIZE .032” X .032” DATE: 3/16/23**

**MFG: CENTRAL THICKNESS .006” P/N: 1N5819**

**DG 10.1.2**

#### Rev B, 7/1